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**INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION**  
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**21 Dec 2007**

**SUBJECT: ON Semiconductor Initial Product/Process Change Notification #16081**

**TITLE: Dual Source ISMF Wafer Fab Qualification for Zener Products**

**PROPOSED FIRST SHIP DATE: 21 Apr 2008**

**AFFECTED CHANGE CATEGORY: ON Semiconductor Fab Site**

**AFFECTED PRODUCT DIVISION: Digital & Consumer Group**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your ON Semiconductor Sales Office or Shilpa Rao <[shilpa.rao@onsemi.com](mailto:shilpa.rao@onsemi.com)>

**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

**DESCRIPTION AND PURPOSE:**

This is the Initial notification announcing that ON Semiconductor is adding wafer fabrication capacity for the Zener/TVS products listed herein at the ISMF wafer fab in Seremban, Malaysia. The ISMF facility is an ON Semiconductor owned wafer fab that has been producing products for ON Semiconductor since 1998. Several existing technologies within ON Semiconductor's product families are currently sourced from ISMF, including Zener Diodes, Small Signal, and USB array filter products.

Quality and performance will be equal to current products. Electrical performance, datasheets and package dimensions will not change.

**Initial Product/Process Change Notification #16081****QUALIFICATION PLAN:**

## Qualification Vehicle:

Qualification vehicles have been carefully selected to address all critical variables and interactions of wafer design features, process considerations, mechanical construction and electrical characteristics. The Qual vehicles & tests include but are not limited to the following:

SMF24CT1G  
SMS05CT1G  
SMS24CT1G

Test:	Conditions:	Interval:	Sample Size: (UnitsxLots)
HTRB	TJ=150C, 80% Rated Voltage	1008 hrs	80 x 3
HTSL	TA=150C	1008 hrs	80 x 3
TC-PC	T= -65C to 150C	1000 cyc	80 x 3



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**AFFECTED DEVICE LIST:**

**PART**

NUP4201MR6T1  
NUP4201MR6T1G  
SMS05CT1  
SMS05CT1G  
SMS12CT1  
SMS12CT1G  
SMS15CT1  
SMS15CT1G  
SMS24CT1  
SMS24CT1G  
LC03-6R2  
LC03-6R2G  
NUP4201DR2  
NUP4201DR2G  
SRDA05-4R2  
SRDA05-4R2G  
SMF05CT1  
SMF05CT1G  
SMF05CT2  
SMF05CT2G  
SMF12CT1  
SMF12CT1G  
SMF15CT1  
SMF15CT1G  
SMF24CT1  
SMF24CT1G